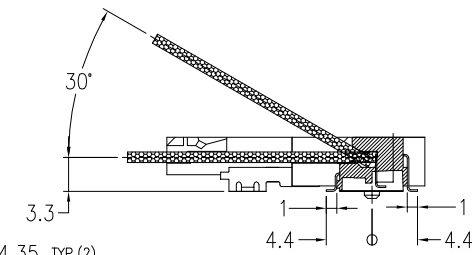
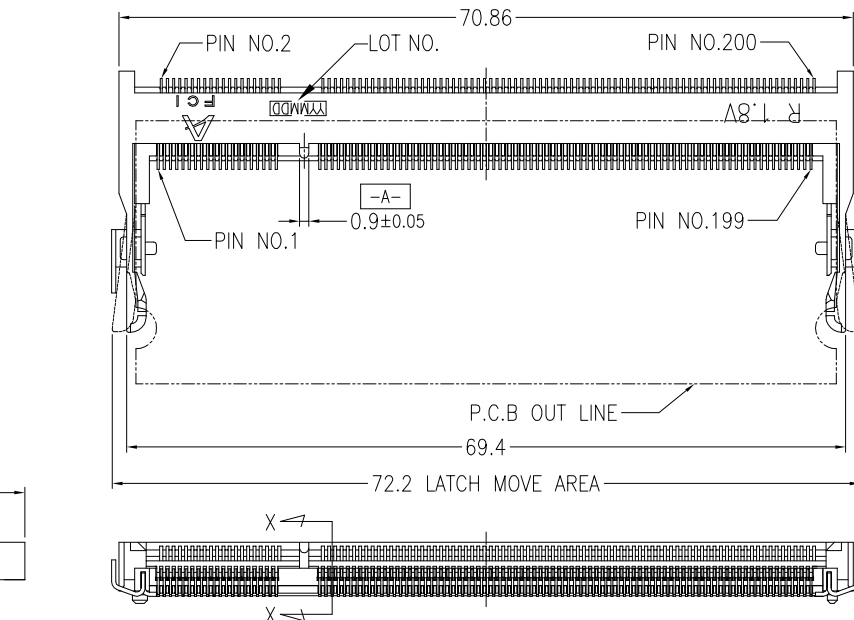
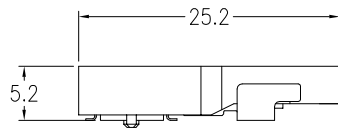
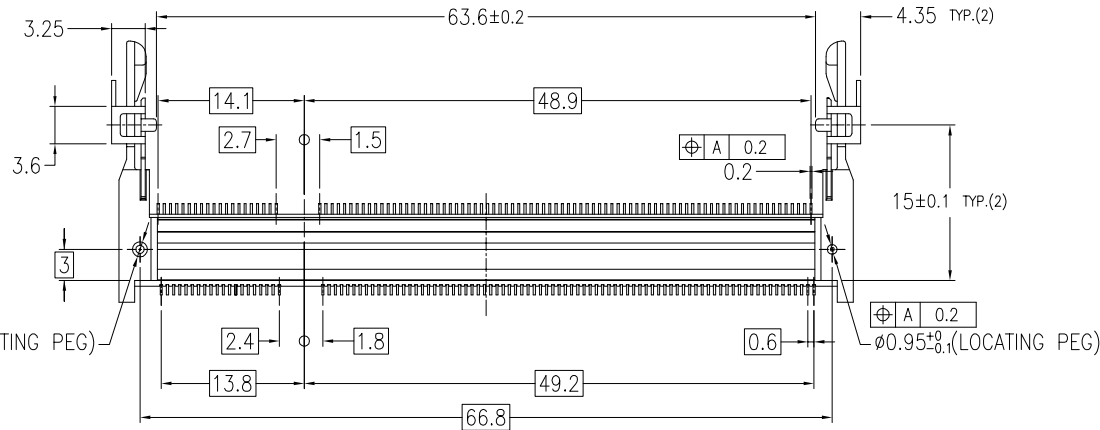


PRODUCT NO.
10033854-*52**

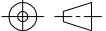


SECT X-X



NOTE

1. PRODUCT SPEC. : GS-12-195
2. PACKAGING SPEC. : GS-14-786
3. MATERIAL
 - 1) HOUSING : LCP, UL94V-0, COLOR BLACK
 - 2) CONTACT : COPPER ALLOY
 - 3) HOLD DOWN : BRASS
4. FINISH
 - 1) TERMINAL : SEE TABLE
 - 2) HOLD DOWN : SEE TABLE
5. CO-PLANARITY : 0.1 MAX.(INCLUDE HOLD DOWN)
6. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
7. THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 10 SECONDS IN A REFLOW SOLDER APPLICATION.

mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		FCI www.fciconnect.com		
ltr	ecn no	dr	date	linear angles	.X ± 0.20		projection 	title DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y			
2		M H	8/28/'03		.XX ± 0.10						
3		M H	4/2/'04								
4		M H	6/29/'04		0° ±5°						
A	J04-0401	M H	9/28/'04	dr	M.Hasegawa	6/29/'04	MM ←————→ scale 2:1	product family 50UF SO-DIMM			code
B	T05-0022	R C	11/9/'04	enrg	M.Hasegawa	6/29/'04		size dwg no			JP
C	T05-0229	R C	10/12/'05	chr				B 10033854			sheet 1 of 4
D	pg08-0333	B L	12/1/'08	appd							
sheet	revision	D	D	D	D						
index	sheet	1	2	3	4						

title

DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y

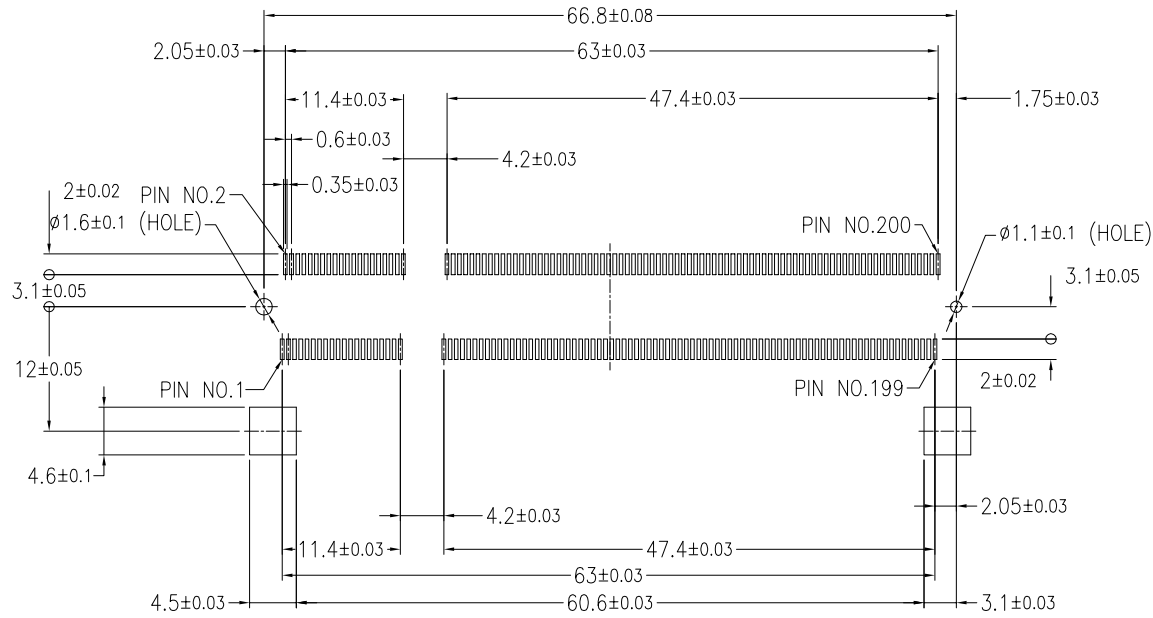
product family 50UF SO-DIMM

size 10033854

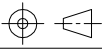
code JP sheet 1 of 4



PRODUCT NO.
10033854-*52**

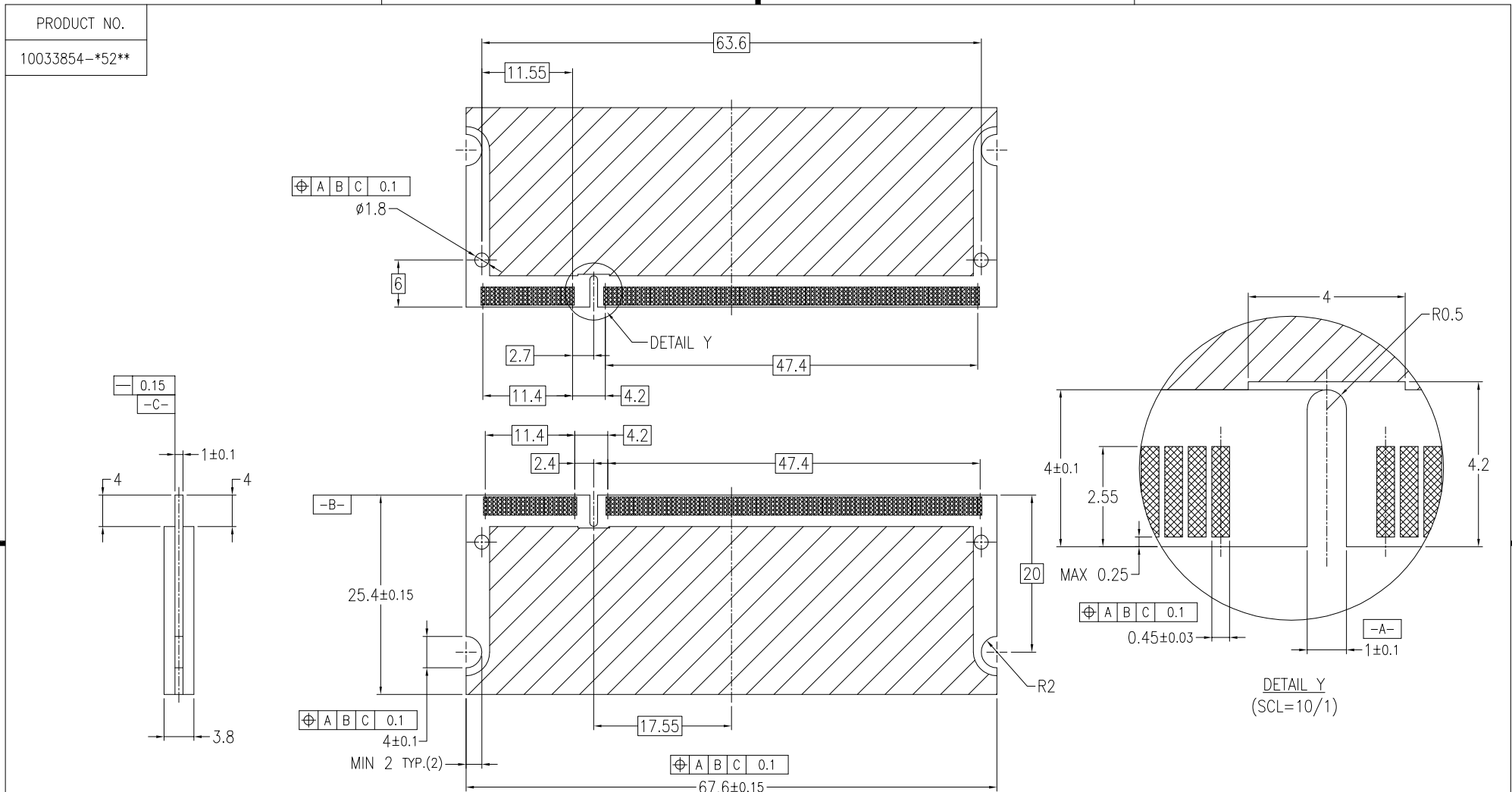


RECOMMENDED MOUNTING P.C.B LAYOUT

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com			
ltr	ecn no	dr	date	linear	.X ± 0.20					
D					.XX ± 0.10	projection	title			
				angles	0° $\pm 5^\circ$		DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y			
				dr	M.Hasegawa	6/29/04	MM	product family		code
				enr	M.Hasegawa	6/29/04		50UF SO-DIMM		JP
				chr			scale	size		sheet
				appd				10033854		2 of
sheet index	revision sheet									

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RECOMMENDED MODULE P.C.B LAYOUT

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		FCI	
ltr	ecn no	dr	date	linear	.X ± 0.20 .XX ± 0.10	projection		title	www.fciconnect.com
D				angles	0° $\pm 5^\circ$			DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y	
				dr	M.Hasegawa 6/29/04	MM		product family 50UF SO-DIMM	code JP
				enr	M.Hasegawa 6/29/04	scale		size dwg no	sheet 3 of
				chr		2:1		B 10033854	
				appd					
sheet index	revision sheet								



PRODUCT NO.	LOCATING PEG	TERMINAL CONTACT AREA FINISH	HOLD DOWN FINISH	SOLDER TAIL FINISH
10033854-052FSLF	YES	Au FLASH	PURE Sn PLATING	Au FLASH
10033854-152FSLF	NO			
10033854-052TSLF	YES	Au 0.3um MIN.		
10033854-152TSLF	NO			
10033854-052ASLF	YES	Au 0.76um MIN.		
10033854-152ASLF	NO			
10033854-052FB	YES	Au FLASH	Sn-Pb PLATING	
10033854-152FB	NO			
10033854-052TB	YES	Au 0.3um MIN.		
10033854-152TB	NO			
10033854-052AB	YES	Au 0.76um MIN.		
10033853-152AB	NO			
10033854-252FSLF	YES	Au FLASH	PURE Sn PLATING	Pure Sn PLATING
10033854-352FSLF	NO			
10033854-252TSLF	YES	Au 0.3um MIN.		
10033854-352TSLF	NO			
10033854-252ASLF	YES	Au 0.76um MIN.		
10033854-352ASLF	NO			
10033854-252FB	YES	Au FLASH	Sn-Pb PLATING	
10033854-352FB	NO			
10033854-252TB	YES	Au 0.3um MIN.		
10033854-352TB	NO			
10033854-252AB	YES	Au 0.76um MIN.		
10033854-352AB	NO			
10033854-452FS	YES	Au FLASH	PURE Sn PLATING	Sn-Pb PLATING
10033854-552FS	NO			
10033854-452TS	YES	Au 0.3um MIN.		
10033854-552TS	NO			
10033854-452AS	YES	Au 0.76um MIN.		
10033854-552AS	NO			
10033854-452FB	YES	Au FLASH	Sn-Pb PLATING	
10033854-552FB	NO			
10033854-452TB	YES	Au 0.3um MIN.		
10033854-552TB	NO			
10033854-452AB	YES	Au 0.76um MIN.		
10033854-552AB	NO			

10033854-□□□□□ LF

<PACKING METHOD>
R : TAPE REEL
DEFAULT : TRAY

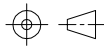
<HOLD DOWN FINISH>
S : Pure Sn
B : Sn-Pb
<CONTACT AREA FINISH>
F : Au FLASH
T : Au 0.3um MIN.
A : Au 0.76um MIN.

<TOTAL HEIGHT>
52 : 5.2mm

<LOCATING PEG, SOLDER TAIL FINISH>
0 : YES, Au FLASH
1 : NO, Au FLASH
2 : YES, Pure Sn PLATING
3 : NO, Pure Sn PLATING
4 : YES, Sn-Pb PLATING
5 : NO, Sn-Pb PLATING

For Rohs OPTIONS:
TAIL PLATING CODE MUST BE 0~3.
HOLD DOWN PLATING CODE MUST BE "S".
"LF" CODE IS EXIST IN THE END.
EX: 10033854-252TSLF

FOR NOT Rohs COMPATIBLE:
THIS "LF" CODE IS "BLANK".
EX:10033854-452TS

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com							
ltr	ecn no	dr	date	linear	.X ± 0.20	projection		title							
D					.XX ± 0.10			DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y							
				angles	0° ±5°			product family 50UF SO-DIMM							
				dr	M.Hasegawa 6/29/04	MM		size							
				engr	M.Hasegawa 6/29/04			dwg no							
				chr		scale	2:1	B							
				appd				10033854							
sheet index	revision sheet														